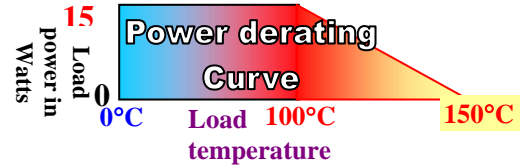
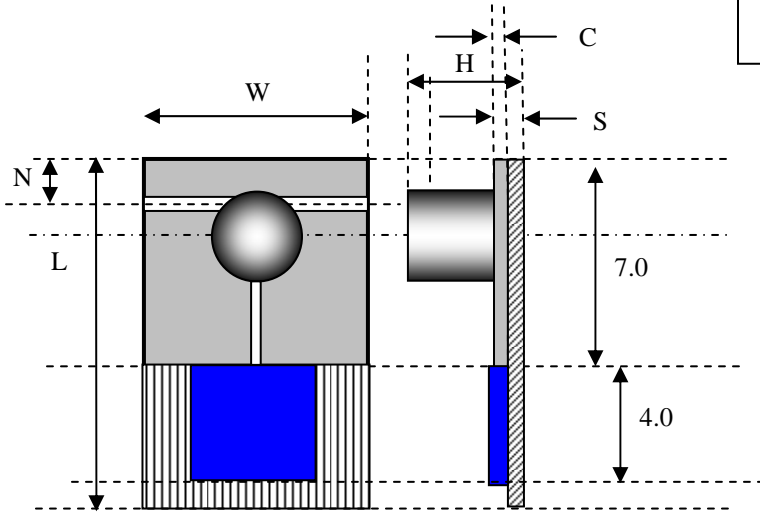


MSSM Metal Backed Substrate Isolator with load
13.7-14.5GHz (10% Bandwidth) 15W or 20W
Ferrite substrate on steel carrier.

code-b

Draft



Operating Temp.	-40 to +70°C
Storage Temp.	-40 to +85°C

Units: mm (inch) **Tolerance +0.00/-0.043 outline, +/- 0.11 Holes/ slot centers**

Note: Dimension S (overall pad height) is critical, Dimension C is for reference only / not critical,

Frequency GHz	I/C	W mm	L mm	H mm max	C mm Ref	N* mm	S +/-0.035 (+/- 0.0014)	In. loss (dB)	Isol. (dB)	VSWR :1	Pwr Fwd (W)	Pwr Rev (W)	Miscellaneous
13.7-14.5	C	7.0	12.0	3.76	0.57	1.5	1.17	0.5	20	1.25	20	20	-40 to +70
13.75-14.5	C	7.1	13.2	3.76	0.57	1.5	1.17	0.5	20	1.25	15	15	-40 to +70

Part # **RADI-13.7-14.5-MSSM-20WR-b** // **RADI-13.75-14.5-MSSM-15WR-b**

Application Notes

- Line width 0.14mm (typical),
- unit should be mounted with thin smear of non conductive epoxy, with temperature of polymerisation close to 80 deg c, but important to leave area around microstrip junctions clear to facilitate grounding.
- Operation Load temperature must be maintained under 80 deg C
- This unit by design will not have as good heat dissipation as a Bolt down unit. Some form of amplifier shut down in sustained high reverse power conditions is recommended
- Distance from a module cover about 1.0 - 1.5mm without any change in performances and about 0.7mm with minimum changes.
- If soldering keep temperature to 130 deg C for 3 - 5 minutes Max.
- If non ultrasonic wedge bonding heat the unit to 150C for 3 minutes max
- Maximum temperature during welding process 350C for 25mSec